

Application No.: 10/805,933

Docket No.: JCLA10375-D

AMENDMENTS**In The Claims:****Claims 1-4 (canceled)**

5. (currently amended) A chip structure with test pads thereon, at least comprising:

a chip with an active surface having at least a flip-chip bonding pad and at least a test pad thereon, wherein the test pad is positioned on the peripheral section of the active surface and is electrically connected to the flip-chip bonding pad, ~~and the chip further has at least a trace line on the active surface for connecting the test pad to the flip-chip bonding pad,~~ the chip further has at least a fuse line buried within the chip and a fuse window having an upper surface below the active surface of the chip for decreasing the thickness of the structure above the fuse line; and

a passivation layer formed over the active surface, wherein the passivation layer exposes the flip-chip bonding pad, ~~and covers the trace line,~~ and fills the fuse window.

Claims 6-7 (canceled)

8. (original) The chip structure of claim 5, wherein the chip furthermore comprises a bump attached to the flip-chip bonding pad.

9. (new) The chip structure of claim 5, wherein the chip furthermore comprises at least a trace line on the active surface for connecting the test pad to the flip-chip bonding pad and the passivation layer also covers the trace line.